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#### CONTATTI

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# **CLEANERS**

ADDITIVES FOR CLEANER		
REMOVA 5122	Alkaline, Chemical and Electrolytic surfactant Agent.	
REMOVER TECHNO 33	Additive for soak and electrolytic cleaners for better results.	Steel
ACID SOAK CLEANER		
REMOVER TECHNO AL 32	Acid product. Oxides removal and degreasing action.	Aluminum
SOAK AND ELECTROL	YTIC CLEANER	
REMOVEL SW 15	Phosphates – free. Product liquid suitable for both soak and electrolytic cleaners.	Steel, Copper, Brass and Cast-Iron
REMOVEL T 11 L	Processing oils removal. Phosphates – free. LIQUID product suitable for soak, electrolytic cleaners and ultrasonic lines.	Steel, Copper and Brass
TECHNIC TEC -1011	Alkaline electrolytic cleaner, phosphates free, it can be used as soak cleaner as well.	Brass ,copper, steel.
ALKALINE SOAK CLEA	ANER	
REMOVER 16 LQ	Buffing compounds. Liquid product.	Brass, Copper ,Silver, Gold, Steel
REMOVER 111	Buffing compounds removal and processing oils removal.	Brass, Copper and Steel
REMOVER 122	Buffing compounds, oils and greases removal.	Brass, Copper and Steel
REMOVER 133 IT	Buffing compounds, oils and greases removal.	Steel and stainless steel
REMOVER FD-102N	Soaking-type alkaline cleaner applicable to iron, copper, aluminum-based metallic materials. Liquid product.	Steel, Copper, Aluminum
REMOVER PB	Buffing compounds and greases removal.	Zamac
REMOVER TECHNO 13	Buffing oils and buffing compounds removal with flocculating action.	Steel, Brass and Copper
REMOVER TECHNO SOLVIT	Buffing compounds removal. Low alkalinity liquid degreaser with deoxidizing action.	Brass, Copper and Tin Alloy
TECHNI TSC 1500	Buffing compounds, greases and oils removal.	Aluminum, Brass, steel, Zamac
TECHNI TSC L2	Liquid product specific for degreasing and removing of polishing paste.	Aluminum, Zamac
ELECTROLYTIC CLEAN	NER	
REMOVEL 555	Cathodic and anodic degreaser.	Brass and Copper
REMOVEL 558	Cathodic and anodic degreaser.	Copper, Brass, Steel, Zamac
REMOVEL 600	Nickel plated surfaces electrolytic activation.	Nickel
REMOVEL 611	Cathodic and anodic degreaser.	Steel
REMOVEL TECHNO 66	No foaming cathodic and anodic degreaser.	Steel, Brass, Copper and Cast iron
TECHNICLEAN SF	Silicates-free, electrolytic, MICROETCHING degreaser for reel to reel system and semiconductors.	Copper, Copper Alloys. Steel, Nickel alloys
TECHNICLEAN OH	Silicates-free, electrolytic, MICROETCHING degreaser for reel to reel system and semiconductors.	Copper, Copper Alloys. Steel, Nickel alloys
REMOVEL 155 IT	Alkaline electrolytic cleaner for still and iron metal. Suitable also for spray application.	Steel
REMOVEL 175 F	Electrolytic alkaline cleaner usable in anodic and cathodic phase.	Brass, Copper, Zamac, Bronze.
SPRAY CLEANER		
	LIQUID cleaner with low foam for spray, ultrasonic and system with air agitation.	Steel
REMOVER FDN - 26	7	

#### **OXIDE REMOVER AND ACID PICKLING ADDITIVES**

ACTIVATOR NI 1	Activator before next plating baths.	Nickel
ACTIVATOR CU	Activator and pickling additive.	Copper and Alloys
REMOVA 95	Activator of metallic surfaces and suitable to remove oxides and silicates. Sulfuric acid substitute.	All metals
REMOVA 97	Neutralizer for silver plated parts with cyanide based electrolytes.	Silver
REMOVA 205	Pickling with brightening action.	Brass
REMOVA 213	Liquid product that increases the pickling action of the sulfuric acid and hydrochloric acid.	Iron
REMOVA 303	Pickling action.	Stainless Steel
REMOVA 316	Acid additive fluorides base for pickling solution.	Steel
REMOVA 1700	Product for difficult pickling and silicates removal.	Aluminum, Copper, Steel, Zinc, Lead.
REMOVA 2011	Acid pickling additive for welding.	Steel and Brass.
REMOVA 2055	Supporting additive for pickling and degreasing action.	Steel
REMOVA 3021	Pickling, with antioxidant and activating action.	Silver
REMOVA 5000 I	Inhibitor for pickling solutions.	Steel
REMOVA 8068	Pickling with degreasing action.	Zamac
REMOVA 8070	Antifumes additive for alkaline zinc electrolytes, acid pickling solutions and alkaline cleaner.	
TECHNIC PST NEUTRALIZER	Slightly alkaline post treatment, designed to remove acid films and oxide from tin and tin-lead plated surfaces.	
STABILIZER IT 30	Process for bright and uniform effect. Hydrogen peroxide based.	Brass and Copper

#### **ZINCATE FOR ALUMINUM**

ALLUMIN 810	Zincate process for next step in copper plating.
ALLUMIN 5200	Zincate process for direct nickel plating.
TECHNI EN ZINCATE	Zincate process suitable for any type of chemicals and electrolytic deposition. CYANIDE FREE.

#### **ELECTROLYTIC DEPOSITION**

BRASS	
BRASS 71 S	Brass electrolytic process with high efficiency. HIGHER ZINC THAN COPPER.
BRASS 71 D	Decorative electrolytic Brass plating process. HIGHER ZINC THAN COPPER.
SURFALAT	Decorative electrolytic Brass plating process.

BRONZE	
TECHNI WHITE EGB	White Bronze potassium based electrolytic process with bright finish. Suitable for hypoallergenic treatment. Normally applied over acid copper,
TECHNI WHITE V	Electrolytic process lead-free of White Bronze whit white and bight aspect. Suitable for hypoallergenic treatment.
IG WHITE	Electrolytic process designed to increase the chemical and physical properties of white bronze. The process replaces Nickel/Phosphorus deposits in nickel-free.

CHROMIUM	
ANTIFUME IG 36 New	Antifumes agent for hexavalent Chrome solutions.
ANTIFUME 66 NF	Fumes dismissive agent for Hexavalent decorative and technique Chrome solution. The solution does not contain PFOS, alcohol or unstable derivatives.
ITALCHROME D/LQ	Decorative hexavalent Chrome plating process with excellent throwing power and high rate deposition.
ITALCHROME NR/5	Hexavalent, black chrome catalyzed bath.
IG CHROME New	Trivalent chromium process.
ITALCHROME HC	Process for heavy chromium deposition with high deposition rate, fluoride free.

ALKALINE COPPER	
GLANCE COPPER PY	Pyrophosphate copper process. Bright deposit.
GLANCE CU 160	Cyanide free, alkaline Copper plating solution.
GLANCE CU 9002	Alkaline Copper plating process containing cyanide and producing very bright deposits. Lead free.

ACID COPPER	
GLANCE AC 300	Dye free, acid copper plating bath.
TECHNI COPPER LUX	Mirror bright acid copper for both rack and barrel.
TECHNIC CU 2300	Copper acid process for PCB (printed circuit boards) and reel-to-reel applications.
TECHNIC CU 2800	Copper acid process for low current density. Suitable for PCB (printed circuits board).
TECHNIC CU SATIN	Revolutionary new electroplating process for depositing copper, where smooth satin deposits are required. Suitable for Decorative applications as well.
ELEVATE CU 6320 New	Electrolytic acid copper process, specifically engineered for plating copper bumps, columns, redistribution layer, UBM and pattern plating on semiconductor. This process operates over a wide range of current densities and produces a fine grain equiaxed, ductile copper deposit.
TECHNI CU NO DYES New	Copper acid process without dyes. Produces deposit with an excellent brightness and throwing power.

GOLD	
AUROTEX 1002 N 14	Electrolytic acid gold plating process that produces 2N14 colors deposits.
AUROTEX 1002 N 18	Acid gold plating solution tolerating relatively high quantities of metal impurities and produces 23.5 karat with 2N18 color deposits.
AUROTEX 1002 NG	Electrolytic, acid gold plating bath producing 23,8 K deposits of "pale gold" color.
AUROTEX 1100 SR	Acid gold process operating at low gold content. For barrel and rack applications.
AUROTEX 240	Decorative gold plating solution at neutral pH.
AUROTEX 290	Decorative gold plating solution with high tolerance to nickel impurities.
AUROTEX 1002 3N	Bright, acidic, Cobalt-Nickel alloy gold plating process for decorative applications. Produces hard deposits at 23.5 karat with 3N color.
AUROTEX AU/FE	Electrolytic process that produces Gold-Iron alloy deposits with high corrosion and abrasion resistance.
AUROTEX 88 GS M	Acid gold plating process suitable to plate directly on stainless steel surfaces.
AUROTEX 94G	Acid gold plating process suitable to plate directly on stainless steel surfaces.

AUROTEX MC 418	Decorative gold plating matching with brass color.
COTE D'OR	Decorative hard Gold.
OROSENE 999 D	Acid, Cobalt/Nickel alloy gold plating bath that produces very bright 24K deposit.
OROSENE 999 E	Heavy acid, Co/Ni alloy based, gold plating process producing very bright 24K deposit.
OROTEMP 24	Neutral gold plating solution with 24 K deposit.
TECHNI ACID GOLD STRIKE	Neutral pure Gold plating solution guaranteeing perfect adhesion. Wood Nickel treatment can be avoided also over passive Nickel hard to plate. It can be used on Stainless Steel, Nickel-Tin, Moly-Manganese alloys, Manganese, Molybdenum, Kovar, Titanium.
TECHNIBOND RM	Neutral pure gold plating process that produces matte to semi-bright, ultrapure, ductile gold deposits that meet the requirements of Type III, Grade A of ASTM B488-01 (Supersedes MIL-G-45204). Semiconductor components, ceramic packages, multichip modules, connectors, contacts or a variety of electronic components.
TECHNI BROWN GOLD	Acid Decorative gold used for getting old gold color in a single step.
TECHNI GOLD 25 ES	It's a neutral NO CYANIDE GOLD plating formulation suitable for electronics, semiconductor, wafer, electroforming, or general applications.
TECHNI GOLD 300	Mildly acidic NICKEL brightened gold plating process for barrel, rack, high speed & selective applications. Nice bright deposit.
TECHNI GOLD 400	Mildly acidic COBALT brightened gold plating process for barrel, rack, high speed & selective applications. Nice bright deposit.
TECHNI-GOLD STRIKE SS	Acid gold for plating over stainless steel with high thickness, suitable also for reel to reel applications. Can be used with Nickel or Cobalt. Usable also as gold strike (that is before gold plating), where necessary, e.g. base materials such as stainless steel, where direct gold plating would not guarantee gold adhesion.
TECHNIC OROSTRIKE C	Gold strike process for decorative and electronic applications.
TECHNI NPD P4	Alkaline, gold plating process that produce Gold/Copper Alloy pink color deposits at 10 karats.
TRUSHADE 24 K	Alkaline, decorative, gold plating process producing a bright 24K deposit.
ELEVATE GOLD 7990 New	Slightly acid, non-cyanide gold plating process suitable for electroplating semiconductors that require a pure, soft gold deposit.

INDIUM	
TECHNI INDIUM HS New	Indium electroplating process designed for connector press-fit pin applications. This process has excellent throwing power and high efficiency.

NICKEL	
GLANCE 189 L	Unique, complete and universal brightener, either for rack or barrel applications.
GLANCE 91 S/A	Electrolytic bright nickel process with levelling effect. Perfect for rack.
GLANCE 374 G	Nickel process with excellent levelling and throwing power on both rack and barrel application.
GLANCE CSF	Semi-Bright Nickel plating for Nickel duplex system.
GLANCE LUX 2	Unique, complete and universal brightener, either for rack or barrel applications specific for fashion accessories.
GLANCE HB	Brightener for semi-bright nickel plating solutions.
GLANCE LUX 1	Unique, universal brightener either for rack or barrel applications.
GLANCE BR 3	Electrolytic Nickel bright process for barrel applications.
TECHNI NICKEL S	Low stress. High deposition rate electrolytic sulfamate Nickel plating process.
STARLUX 50	Unique, universal brightener either for rack or barrel.

TECHNO MAGIC 11	Unique, universal brightener either for rack or barrel applications. Very soft deposits and amazing throwing power.
GLANCE LUX 4 New	Electrolytic nickel process that produces bright deposits in barrel applications.
GLANCE 91 S New	Electrolytic nickel process suitable for Iron treatment in rack applications.
ELEVATE NI 5910 New	Process designed to produce a low stress, ductile nickel deposit for semiconductor applications.
GOLDENEYE NICKEL	Nickel plating process for reel-to-reel, rack and barrel application with high distribution thickness. Produces deposits with low internal stress and high corrosion resistance.
GOLDENEYE NICKEL ORC	Nickel plating process designed to protect Tin deposits from discoloration due to thermal exposure (es. reflow).
GOLDENEYE LEVEL NICKEL	Nickel plating process that produces leveled and bright deposits in high speed, rack or barrel applications. The deposits have high hardness and corrosion resistance.
GOLDENEYE NICKEL II New	Nickel plating process that provides improved performance vs. standard nickel sulfamate or sulfate solutions in connector reel-to-reel plating applications.
GOLDENEYE SATIN NICKEL	Process which produces a smooth satin nickel deposit.
GOLDENEYE MATTE NICKEL	Nickel plating process that produces matte deposits with high ductility, low internal stress and good corrosion resistance in Reel-to-Reel applications. Meets the specifications AMS-QQ-N-290B (Rev. 2009 – 07) Class 1 "SD".
GOLDENEYE LEVEL NICKEL HS	Advanced electroplating process designed to produce fully bright lustrous nickel deposits at high current density, suitable for decorative applications.
NIST AS 233	Satin nickel plating process.
NIST SF 512 New	Satin nickel plating process.
NIST WL 835 New	Satin nickel plating process.

NICKEL ALLOY	
BLACK GUN CL	Black Nickel-Tin process
GLANCE N 23	Dark grey nickel plating process.
GLANCE NI SP3	Electrolytic Phosphorous nickel plating process, developed to increase the corrosion resistance of metal accessories plated by this bath.
DURATECH NIW New	Electrolytic process that produces deposits alloy of Nickel-Tungsten. Could replace the hard chrome deposits.
MARK 1046	Electrolytic Cobalt-Nickel plating process designed for producing variegated, iridescent color.
GOLDENEYE NICKEL New TUNGSTEN	Electrolytic process that produces deposits alloy of Nickel-Tungsten. It is suitable for electronic applications.

PALLADIUM	
PALLASPEED VHS	Electrolytic Palladium process with high deposition rate for high speed applications.
PALLASPEED VHS D	Electrolytic Palladium process for decorative applications.

PALLADIUM ALLOY	
TECHNIC PALLADIUM NICKEL VHS	Palladium/Nickel alloy, semi-bright to bright aspect (70-90% Palladium). Conventional Pd/Ni plating process. Chloride based electrolyte.
TECHNIPAL PF	Pd/Fe alloy bright deposit, cobalt and nickel free.

PLATINUM	
PLATINUM AP	Electroplating process which deposits a hard platinum coating from a neutral pH bath. Platinum AP has an excellent adhesion on most substrates. Highly recommended for industrial applications.

ELEVATE PLATINUM 7810 New	Mildly acid platinum plating solution formulated for MEMS, semiconductors and other applications that require a bright low-stress and heavy deposit of platinum.
RHODIUM	
RHODIUM IT 2	Decorative, electrolytic Rhodium plating process.
TECHNI DARK RHODIUM New	Electroplating process designed to deposit a uniformly thin, hard, dark rhodium coating.
RHODIUM ALLOY	
TECHNI WHITE New RHODIUM/PALLADIUM	Electroplating process designed to deposit a uniform bright, white, low stress rhodium-palladium coatings.
TECHNI WHITE New RHODIUM/RUTHENIUM	Electroplating process designed to deposit a uniform bright, white, low stress rhodium-ruthenium coatings.
RUTHENIUM	
RUTHENIUM AK New	Ruthenium process suitable for barrel application. It produces deep grey color to anthracite color.
RUTHENIUM-U	Ruthenium bath of grey color deposit for rack applications.
SILVER	
ACR 1050	High speed silver process. For semiconductor and electronics industry.
SILVER IT 2	Electrolytic Silver plating process for industrial applications, Potassium Cyanide based, producing semi-bright deposit.
SILVERSENE DW	Electrolytic Silver plating process, Potassium Cyanide based, producing mirror-bright deposits.
SILVERTEK L	Decorative Silver plating solution, with white and bright deposits (Organic Brightener).
TECHNI SILVER CY LESS II W	CYANIDE FREE, electrolytic Silver plating process with BRIGHT deposits.
TECHNI SILVER CY LESS II W SEMIBRIGHT	CYANIDE FREE, alkaline, electrolytic Silver plating process with SEMI BRIGHT deposits.
TECHNI SILVER E	Potassium Cyanide based Silver plating bath with bright deposit. (Metallic Brightener).
TECHNI SILVER EHS 3R	High speed silver pure process operates at very low concentration of free cyanide. It can reach very high current density, (till 400 Amp/dm²).
TIN	
JB 3000 DECORATIVE	Completely full bright and very white deposit, ideal for decorative sector.
TECHNI BT 2	Sulfate based electrolytic Tin plating process, with bright deposits, for barrel and rack applications.
TECHNI MATTE TIN SULFATE 89TI	Sulfate based matte tin plating process, for rack and barrel applications.
TECHNI NF JB 3000	High speed bright tin plating process. MSA based electrolyte. Bright tin whiskers resistant. Satisfies all requirements of JEDEC JESD 201.
TECHNI NF JM 3000	High speed pure matte-satin tin process for reel-to-reel continuous strip applications. MSA based. Fully compatible with Techni NF JB 3000 bright tin.
TECHNISTAN JM 7000	Matte Tin process suitable in rack, barrel and high speed applications, appropriate for electronics components, semiconductor and connectors. It's a process based on Sulfuric acid which produces deposits lead-free.

**TECHNISTAN JM 8000** 

New matte Tin process designed for the ultra high, high, and medium speed deposition in electronic plating applications, such as semiconductors, frames and connectors. It's a process based on methane sulfonic acid, which produces lead-free deposits.

TECHNI SOLDER NF-W	High speed matte tin process for WIRE. MSA based, produces a matte-satin deposit.
TECHNISTAN TP 5000	High speed MATTE pure tin process for reel-to-reel continuous strip applications. SULFURIC ACID BASED. Offers significant cost advantages vs MSA system.
TECHNISTAN TP W	High speed matte /satin pure tin for <b>WIRE</b> applications. Based on SULFURIC ACID technology. It offers significant cost advantages vs the MSA system.
TECHNIBRITE HT 1000	Bright acid Tin process, with sulfuric-base and nonylphenol Free. Process suitable for rack and barrel applications, works over a wide range of current densities.
TECHNI NF JM 6000 LS	Electrolytic matte Tin process for low speed rack and barrel applications. Provides a white/grey matte deposit, from a methane sulfuric acid based system.
TECHNI BT 1000	Process which produces mirror bright pure tin deposits from sulfate based electrolyte. It is designed for high speed and medium speed depositions in electronic applications.

TIN ALLOY	
BLACK TIN COBALT	Tin/Cobalt process for barrel applications. Dark-grey deposits.
TECHNISTAN AG	Semi bright high speed Tin/Silver alloy plating process (93-99% tin) for CONNECTOR applications. Excellent whisker resistance.
TIN COBALT	Tin-Cobalt alloy based bath, with light aspect, Chrome like. Suitable for rack and barrel application.

ZINC	
ALPHALUX	Alkaline cyanide free process, with very bright deposits. Suitable for rack and barrel applications.
BETALUX BARREL	Alkaline cyanide free zinc process for barrel applications. Produces mirror deposits with good throwing power.
BETALUX RACK	Alkaline cyanide free zinc process for rack applications. Produces mirror deposits with good throwing power.
SIRIO 600	Versatile potassium chloride zinc plating process. Boron free. Ideal for barrel applications.
SIRIO 1000	Acid zinc electroplating process, based on potassium chloride with excellent brightness and low concentration of surfactant agent. Ideal for barrel ad rack applications. Usable also when hot.
VEGA 2500	Alkaline cyanide based bright process. Can be used both rack and barrel applications.
VEGA 3000	Acid chloride zinc plating bath. Suitable for rack and barrel applications.
VEGA W 28	Acid sulfate based process for reel to reel applications. Semi bright. Ideal for wire and strips.

ZINC ALLOY	
VEGA ZF 210	Alkaline zinc-iron process with high corrosion resistance. Can be used both rack and barrel applications.
SHEDAR 30	Alkaline Zinc-nickel process with uniform appearance. Ideal for barrel and rack applications.

# **ELECTROLESS AND IMMERSION METAL DEPOSITION**

ELECTROLESS NICHEL	
TECHNI EN 4100	Alkaline Electroless nickel strike ideal for Aluminum.

TECHNIC EN AT 5600	Advanced, electroless nickel that produces a deposit with 6 – 8% w/w phosphorus. It is specifically formulated for use with TechniPad ENIG and TechniPad ENEPIG processes for PCB (printed circuit boards) and it meets IPC4552.
TECHNI EN AT 5300	Low phosphorous bright electroless nickel that produces a compressive stress hard deposit, with excellent corrosion resistance in alkaline environments.
TECHNI EN 6500 PT	LEAD AND CADMIUM-FREE, electroless nickel medium Phosphorous. Bright deposit, high speed bath.
TECHNI EN 9155	Semi-bright high phosphorous, with high corrosion resistance. Self-regulated pH.
TECHNI EN 9500	Electroless nickel with two components at low temperature. Ideal for plastic.
TECHNI EN 3500 TF	Advanced High Phosphorus Electroless Nickel Process, designed to deposit a uniform, nickel phosphorus composite alloy with ultra-fine PTFE particles.

ELECTROLESS PALLADIUM	
TECHNICATALYST AT 4000	Chloride free activator to produce an immersion Palladium deposit, for initiation of Nickel reduction on Copper, Copper alloys and other non-catalyst substrates prior to electroless nickel.
TECHNI PD ACTIVATOR	Activator Copper and Brass surfaces to be treated with process of electroless Nickel and Gold.

IMMERSION GOLD	
TECHNI IM GOLD AT6000	Self limiting immersion gold bath for optimum solderability. Ideal for PCB.
OROMERSE-SO	NO CYANIDE immersion gold process, developed to deposit up to 1 micron of gold onto electroless-nickel (low or high phosphorous content) and copper.
OROMERSE MN	Immersion gold process formulated to produce 0,1 – 0,2 µm gold deposits over several types of electrolytic and electroless deposits. Suitable for brass, copper, silver and electroless Nickel.
TECHNIPAD AU 6100 New	Cyanide based immersion gold plating process designed to provide a thin pure gold deposits onto electroless nickel and electroless palladium.

IMMERSION SILVER	
ARGENTOMERSE NC	NO CYANIDE immersion silver. Nitrate free.

IMMERSION TIN	
STANOMERSE	Immersion Tin, easy to use on Brass and Copper.
TECHSTAN AL New	Immersion Tin process, designed to promote adhesion of electroplated metallic coatings on Aluminum and Aluminum alloys substrates avoiding the use of product containing zinc.

# PASSIVATION – FINISHING AGENT – TOP COAT

BRASS	
PROTEX 65	Liquid protective product, it prevents oxidation and stains over copper alloys. Can be used without rinse after.
TARNIBAN 2000	Chrome free, metallic Passivation for Brass and Copper. Produces thin, inorganic film that can be painted.
GOLD	
TARNIBAN KS II	Can be applied by immersion or anodically for increase protection. Passes sulfide tests. Chrome free.

SILVER	
TARNIBAN 51	Produces INORGANIC, thin, colorless and paintable film, with good resistance to corrosion with improved solderability and no effect on electrical performance.

TARNIBAN KS II	Can be applied by immersion or anodically for increase protection. Passes sulfide tests. Chrome free.	
NICHEL		
TECHNISEAL New	Cathodic electrolytic passivation system, based on trivalent chromium, that provides a transparent nano-scale coating on black electroless nickel coatings.	

TIN	
TARNIBAN C 50	Provides protection of tin and tin alloy from the discoloration following exposure to high humidity/steam environments plus dry thermal exposure (Reflow/oven bake).
TARNIBAN C 48	Specifically designed for use on tin and tin alloy deposits, which are subjected to post-plate thermal exposure in high humidity/steam environments. For optimal results, Tarniban C 48 should be used in combination with Techni PST Neutralizer. Suitable also for Nickel and Copper.
TARNIBAN E 260	Post treatment process to protect Tin and Tin alloy deposits from oxidation and discoloration when subjected to thermal conditioning, i.e. reflow.

ZINC	
TOPCOAT 11	Sealer for zinc plated and passivated surfaces.
TOPCOAT 14	Specially formulated organo-mineral liquid concentrate used to increase corrosion protection to zinc and zinc-alloys electroplated surfaces (Zn/Ni, Zn/Fe).
TOPCOAT IG 21 New	Sealer in emulsion to increase the corrosion resistance, specific for low friction coefficient.
METASU YC-T (I) New	Clear Top Coat/Sealer, water-based.
METASU LUBRUS KE 1(I) New	Chrome free black top coat agent with high corrosion resistance.
METASU LUBRUS CE 1 (I) New	Chrome free clear top coat agent with high corrosion resistance.
WONDER CFY 1	Trivalent chromium BLUE conversion, COBALT FREE, HIGH CORROSION RESISTANCE for acid and alkaline processes.
WONDER GR 14	Trivalent chromium conversion. HIGH CORROSION RESISTANCE for acid and alkaline processes.
WONDER SB 18	Trivalent chromate BLUE conversion, for zinc acid or alkaline, with or without cyanide. It contains Cobalt.
WONDER SH 4	Trivalent Chrome based Chromate Conversion, Coating of YELLOW IRIDESCENT color. Pale color.
WONDER TR 36	Trivalent chromium BLUE conversion, COBALT FREE for acid and alkaline processes.
WONDER Z 1	Hexavalent Chrome based Chromate Conversion, Coating of black color.
WONDER Z 7	Trivalent Chrome Conversion Coating of bright black color, for alkaline Zinc.
WONDER Z 20	Hexavalent Conversion Coating of bright green olive color.
WONDER Z 89 L	Hexavalent Chrome based Chromate Conversion Coating of yellow iridescent color.
WONDER ZA/B	Trivalent chrome conversion coating for dip black and high corrosion resistance for alkaline zinc.
WONDER Z BSR	Trivalent Chrome based Chromate Conversion Coating of blue, Silver (white) and rainbow (iridescent) colors. High corrosion resistance.
WONDER 11 A/B New	Trivalent chrome black conversion for Zinc/Nickel deposits.
WONDER CYN 11 A New	Trivalent chrome blue conversion for Zinc/Nickel deposits.
WONDER Z BL 30 New	Trivalent chromium BLUE conversion COBALT FREE, for acid and alkaline processes.

# **METALLOCHROMY**

MARK 15	Chemical process of vivid blue color.	Silver, nickel, iron
MARK 10 L	Chemical darkening process, used as conditioner for Brass.	Brass
MARK 20 L	Blackening process by chemical dip.	Copper, Brass and alloys.
MARK 25 S	Green-copper color at room temperature.	Copper, Brass and alloys.
MARK 30	Direct blackening of iron surfaces. HIGH TEMPERATURE	Iron
MARK 45	Darkening process for stainless steel. HIGH TEMPERATURE	Stainless steel.
MARK 60	Blackening process with blue reflection.	Silver.

MARK 71	Blackening process with black reflection, easy to brush for old effect.	Silver.
TECH OX P	Blackening process with raven-black reflection.	Silver.
MARK 80 S	Blackening chemical dip.	Zinc and Zamac
MARK 130	Chemical dip process for ancient bronze color, with reddish reflections.	Copper and Brass
MARK 500	Chemical dip process for ancient bronze color.	Copper and Brass
MARK 511	Chemical dip process for dark bronze color.	Copper, Brass and Nickel
MARK 350 P	POWDER PRODUCT for ancient bronze color.	Copper and Brass
MARK 833	Chemical dip process for black color.	Brass
MARK 5333	Room temperature direct blackening process for iron, steel and cast-iron.	Steel and Cast iron
MARK A 380	Room temperature blackening solution for Aluminum.	Aluminum
MARK SS 73	Room temperature direct blackening process for STAINLESS STEEL.	Stainless steel

#### **METAL STRIPPERS**

KEMSTRIP 41	Electrolytic anodic stripper for racks. Suitable for all metals.	
KEMSTRIP 700 B	Electrolytic anodic Stripper for racks. ONE COMPONENT. Suitable for all metals.	
KEMSTRIP AF/S	Metal stripper developed for removing deposits of nickel, copper and brass from steel, by simple chemical immersion of parts, without etching the metal underneath. Operates with cyanide.	
KEMSTRIP AU 92/P	Stripper designed for removing gold deposits from Brass, Copper and Nickel by simple chemical immersion.  Operates with cyanide.	
KEMSTRIP CU 15	CYANIDE FREE liquid process to remove COPPER from steel and Nickel.	
KEMSTRIP NI 87	Acid stripper to remove Nickel from brass and copper.	
KEMSTRIP NI A/B	CYANIDE FREE liquid process to remove nickel only for immersion from Iron, Copper and Brass.	
KEMSTRIP NI Z	CYANIDE FREE liquid process to remove nickel from zamac plated with copper. For a short period it doesn't etch zamac surface not well plated by Copper.	
KEMSTRIP SN 60	Acidic stripper to remove tin and tin/lead from brass and copper	
TECHNIC ENVIROSTRIP AG	Electrolytic inversed-current process, completely CYANIDE FREE, specifically formulated for removing silver deposits from metallic under-layer as copper, brass and nickel. It does not produce fumes during the metal removal.	
TECHNI STRIP SILVER SPECIAL	Stripper based on Sodium Cyanide, has been formulated in order to eliminate, chemically, silver deposits from nickel surfaces, nickel alloys, copper, copper alloys and steel (iron), without damaging the base metal.	
TECHN SOLDER STRIPPER JA	Immersion-type stripper, it quickly and effectively removes tin, tin-lead, bronze and Tin/Cobalt deposits from Brass and Copper. Techni Solder Strip JA is a liquid concentrate in addition must be used hydrogen peroxide.	
ACR 9050 PALLADIUM STRIPPER	Chemical stripper for removing Palladium and Palladium-Nickel alloys. It contains cyanide.	
TECHNI EIP 1700	No cyanide stripper for electroless nickel low, medium and high P, used in soak or electrolytic condition.	

#### **DRYING AND PROTECTIVE PRODUCTS**

PROTEX 73 Dryer and antioxidant for steel and cast iron.				
PROTEX 87	Protective oil for emulsion, particularly suitable as post treatment after blackening. Suitable for steel.			
TECHNI AQUA SHED 1	Aqueous mixture with dewatering action. Suitable for all metals.			
PROTEX 18 S New	Oil for emulsion, suitable for iron protection, carbon steel and cast iron.			

#### **STRIPPER FOR VARNISHES AND PAINTS**

REMOVA RA	Acid, not aqueous compound, used at full concentration, for removing epoxy enamels of difficult removal from almost all substrates. It can be used also to remove transparent or colored cataphoretic lacquer. The removal takes place by wrinkling of the enamels.
REMOVA RH	Strongly acid, not aqueous compound, used at full concentration, for removing epoxy enamels and resins of difficult removal from steel.
REMOVA RY	Acid, not aqueous compound, used at full concentration, for removing epoxy enamels and resins of difficult removal from steel.

#### **VARNISHES**

112 ETCH PLATING	Removable paint to be used as protection to the etching action in the glass industry.			
HIDROSOL 2002	The HYDROSOL-2002 is a colorless and transparent water-based lacquer developed for protecting metals the more than others, are subject to the oxidation for example Brass, Copper, Bronze, Iron, etc.			
BLUE PEELABLE PAINT	Removable paint to be used as protection for surfaces that must not be electroplated.			
VERNICE ZAPON TRASPARENTE	Transparent varnish, particularly suitable to protect several types of metals like: brass, copper, bronze, iron etc. It is also recommended as final protection of galvanized articles as: brass plated, gold plated parts, etc.			
GLOSSYCLEAR W 1	Transparent varnish in water matrix. Dry in oven.			
YELLOW PEELABLE PAINT	Protective paint based on PVC, used for masking parts to submit to electroplating treatment, avoiding the covering of painted parts.			

# **CATHAPHORETIC LACQUER**

TECHNICLEAR 1100	Cataphoretic lacquer that produces transparent coatings.				
INTEGRAL DYE SERIER	Color additive for transparent cataphoretic lacquer. Available colors:  - Black Integral Dye - Yellow Integral Dye - Red Integral Dye - Blue Integral Dye - White Integral Dye - Gold Integral Dye - Green Integral Dye It is possible to obtain other shades mixing the standard colors.				
POST DYE SERIES	Color for cataphoretic lacquer applicable as subsequent passage. Available colors:  - Brass Post Dye  - Copper Post Dye  - Standard Gold Post Dye  - Special Gold Post Dye  - Bronze Post Dye  - Antique Bronze Post Dye  - Black Post Dye  - Red Post Dye  - Blue Post Dye  - Blue Post Dye.  - Green Post Dye.  - Purple Post Dye				

#### **3D PRODUCT**

TECHNI PRINT 3D SUPPORT CLEANER New	Special product formulated for removing stratasys sr series support material. It is recommended for use in all support removal equipment.
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# **MISCELLANEOUS**

ELECTROBRIGHT F6	Bright anodic electropolishing for stainless steel.
TECHNI GOLD ADDITIVE AIA	Product which minimizes or prevents gold immersion onto nickel substrates during high speed and selective plating in any gold solution.
TECHNI GOLD LCD POLARIZER	Additive specially formulated to inhibit the deposition of gold in low current density areas in gold plating solutions, in applications where this capability is desired.
TECHNI NI PURIFIER	Complexing agent for electroplating nickel baths, used to remove metallic contamination.
TECHNI TIN LEAD CLEAR A FLOCK	Recommended for use in tin and tin alloys baths. Acts by coagulating and precipitating the stannic tin. Can be readily filtered, leaving behind a clear plating bath.
ANTISCHIUMA 24 ER	SILICONS FREE agent, with 100% of active substance. Very stable in both acid and basic ambient. It doesn't produce foam when the temperature increases.
TECHI ADDITIVE AU	Stabilizer product for acid gold plating solution.
TECHNISTAN ANTIFOAM	Antifoam for all type of tin baths. Does not contain silicone.

### **NOTES**



